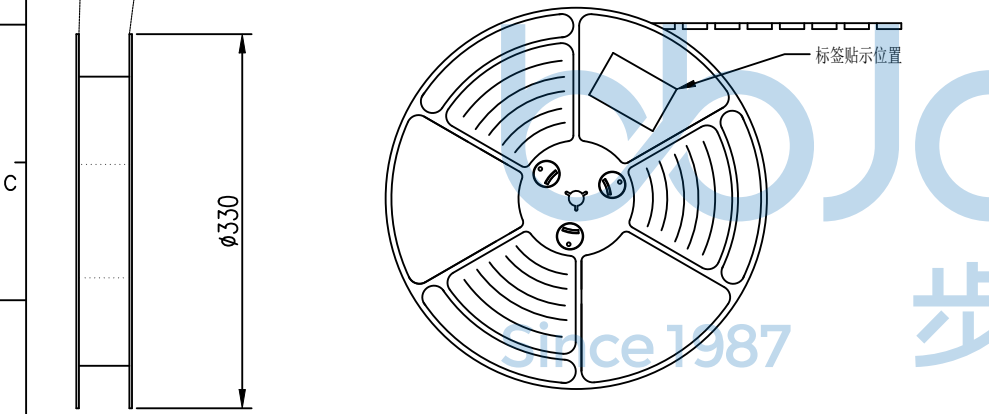
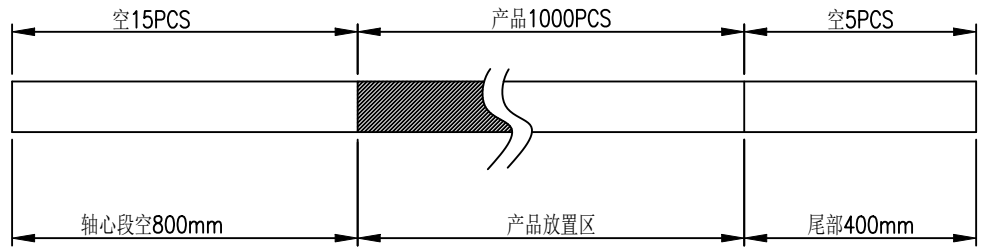
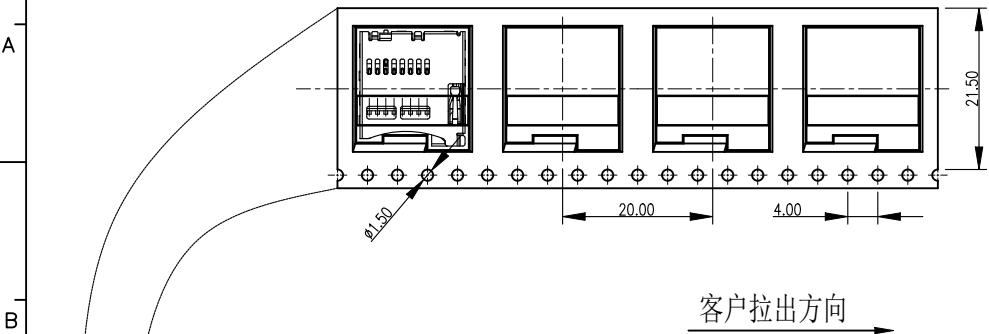




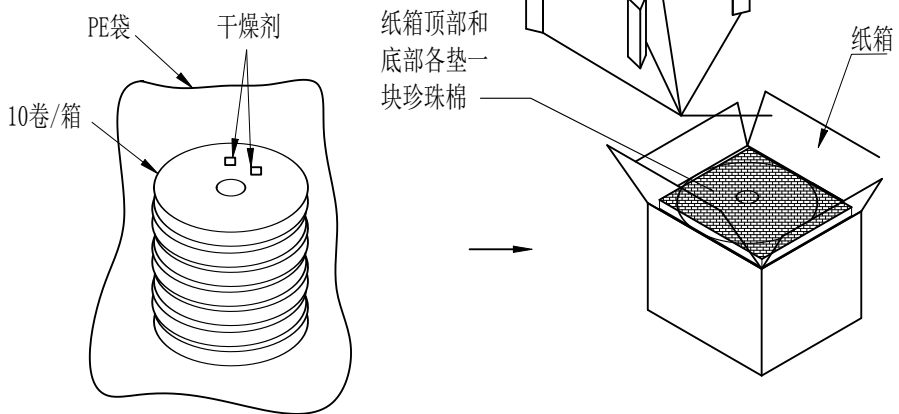
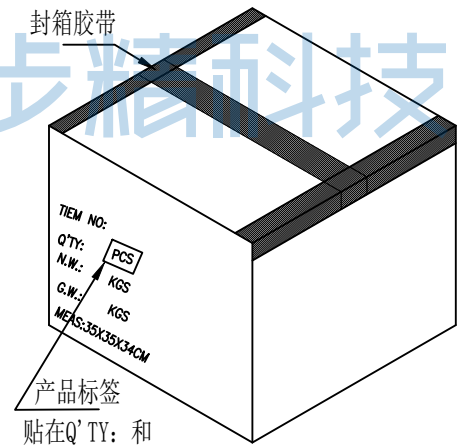
REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP
A1	EN2308009	焊接区由镀锡改为镀金G/F	2023/8/16	TSP

NOTES

- 每卷包装数量:1000PCS/每卷
- 卷带包装方式:



- 每箱包装数量:10000PCS/箱



THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co.,Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		<b>深圳市步步精科技有限公司</b>	
.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X*: ±3* X*: ±2* XX*: ±1*	
APPD. JM_Zheng		NAME: 卡座 TF CARD PUSH PUSH H=1.85 常开一体式 贴片 无柱	
CHKD. LYX		PJ. NO.: CD.01.02-13-0001	
DR. TSP		SIZE: A4 DRW NO.:	
PDWG.NO: 0302-1		FINISH: SEE NOTES MAT'L.: SEE NOTES	
		SCALE: N/A REV.: A1 UNIT: mm PAGE: 2/2	